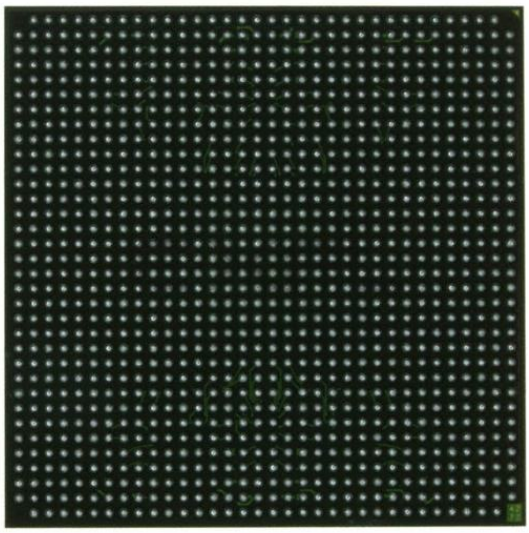
AMD Xilinx - XC2VP20-7FFG1152C Datasheet



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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	2320
Number of Logic Elements/Cells	20880
Total RAM Bits	1622016
Number of I/O	564
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc2vp20-7ffg1152c

Virtex-II Pro and Virtex-II Pro X Platform FPGAs: Functional Description

DS083 (v5.0) June 21, 2011 **Product Specification**

Virtex-II Pro[1] Array Functional Description

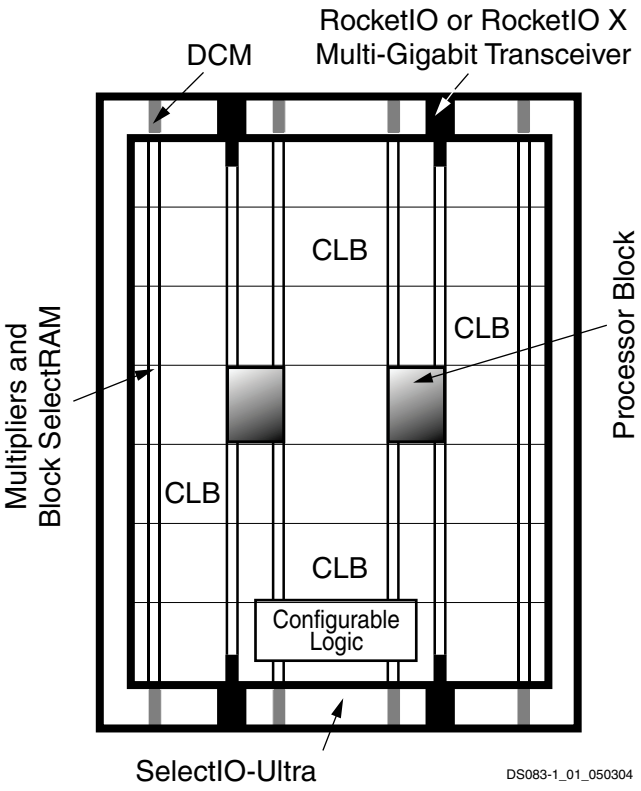


Figure 1: **Virtex-II Pro Generic Architecture Overview**

This module describes the following Virtex™-II Pro functional components, as shown in Figure 1:

- Embedded RocketIO™ (up to 3.125 Gb/s) or RocketIO X (up to 6.25 Gb/s) Multi-Gigabit Transceivers (MGTs)
- Processor blocks with embedded IBM PowerPC™ 405 RISC CPU core (PPC405) and integration circuitry.
- FPGA fabric based on Virtex-II architecture.

Virtex-II Pro User Guides

Virtex-II Pro User Guides cover theory of operation in more detail, and include implementation details, primitives and attributes, command/instruction sets, and many HDL code examples where appropriate. All parameter specifications are given only in Module 3 of this Data Sheet.

These User Guides are available:

- For detailed descriptions of PPC405 embedded core programming models and internal core operations, see **PowerPC Processor Reference Guide** and **PowerPC 405 Processor Block Reference Guide**.
- For detailed RocketIO transceiver digital/analog design considerations, see **RocketIO Transceiver User Guide**.
- For detailed RocketIO X transceiver digital/analog design considerations, see **RocketIO X Transceiver User Guide**,
- For detailed descriptions of the FPGA fabric (CLB, IOB, DCM, etc.), see **Virtex-II Pro Platform FPGA User Guide**.

All of the documents above, as well as a complete listing and description of Xilinx-developed Intellectual Property cores for Virtex-II Pro, are available on the Xilinx website.

Contents of This Module

Virtex-II Pro Compared to Virtex-II Devices

Virtex-II Pro devices are built on the Virtex-II FPGA architecture. Most FPGA features are identical to Virtex-II devices. Major differences are described below:

- The Virtex-II Pro FPGA family is the first to incorporate embedded PPC405 and RocketIO/RocketIO X cores.
- V_{CCAUX}, the auxiliary supply voltage, is 2.5V instead of 3.3V as for Virtex-II devices. Advanced processing at 0.13 µm has resulted in a smaller die, faster speed, and lower power consumption.
- Virtex-II Pro devices are neither bitstream-compatible nor pin-compatible with Virtex-II devices. However, Virtex-II designs can be compiled into Virtex-II Pro devices.
- On-chip input LVDS differential termination is available.
- SSTL3, AGP-2X/AGP, LVPECL_33, LVDS_33, and LVDSEXT_33 standards are not supported.
- The open-drain output pin TDO does not have an internal pull-up resistor.

1. Unless otherwise noted, "Virtex-II Pro" refers to members of the Virtex-II Pro and/or Virtex-II Pro X families.

Output Swing and Emphasis

The output swing and emphasis levels are fully programmable. Each is controlled via attributes at configuration, and can be modified via the PMA attribute programming bus.

The programmable output swing control can adjust the differential peak-to-peak output level between 200 mV and 1600 mV.

With emphasis, the differential voltage swing is boosted to create a stronger rising or falling waveform. This method compensates for high frequency loss in the transmission media that would otherwise limit the magnitude of this waveform. Lossy transmission lines cause the dissipation of electrical energy. This emphasis technique extends the distance that signals can be driven down lossy line media and increases the signal-to-noise ratio at the receiver.

Emphasis can be described from two perspectives, additive to the smaller voltage (V_{SM}) (pre-emphasis) or subtractive from the larger voltage (V_{LG}) (de-emphasis). The resulting benefits in compensating for channel loss are identical. It is simply a relative way of specifying the effect at the transmitter.

The equations for calculating pre-emphasis as a percentage and dB are as follows:

$$\text{Pre-Emphasis}_{\%} = ((V_{LG}-V_{SM}) / V_{SM}) \times 100$$
$$\text{Pre-Emphasis}_{dB} = 20 \log(V_{LG}/V_{SM})$$

The equations for calculating de-emphasis as a percentage and dB are as follows:

$$\text{De-Emphasis}_{\%} = (V_{LG} - V_{SM}) / V_{LG}) \times 100$$
$$\text{De-Emphasis}_{dB} = 20 \log(V_{SM}/V_{LG})$$

The pre-emphasis amount can be programmed in discrete steps between 0% and 500%. The de-emphasis amount can be programmed in discrete steps between 0% and 83%.

Serializer

The serializer multiplies the reference frequency provided on REFCLK by 10, 16, 20, 32, or 40, depending on the operation mode. The multiplication of the clock is achieved by using an embedded PLL.

Data is converted from parallel to serial format and transmitted on the TXP and TXN differential outputs. The electrical connection of TXP and TXN can be interchanged through configuration. This option can be controlled by an input (TXPOLARITY) at the FPGA transmitter interface.

Deserializer

Synchronous serial data reception is facilitated by a clock and data recovery (CDR) circuit. This circuit uses a fully monolithic Phase Lock Loop (PLL), which does not require any external components. The CDR circuit extracts both phase and frequency from the incoming data stream.

The derived clock, RXRECCLK, is generated and locked to as long as it remains within the specified component range. This clock is presented to the FPGA fabric at $^1/_{10}$, $^1/_{16}$, $^1/_{20}$, $^1/_{32}$, or $^1/_{40}$ the incoming data rate depending on the operating mode.

A sufficient number of transitions must be present in the data stream for CDR to work properly. The CDR circuit is guaranteed to work with 8B/10B and 64B/66B encoding. Further, CDR requires approximately 5,000 transitions upon power-up to guarantee locking to the incoming data rate. Once lock is achieved, up to 75 missing transitions can be tolerated before lock to the incoming data stream is lost.

Another feature of CDR is its ability to accept an external precision reference clock, REFCLK, which either acts to clock incoming data or to assist in synchronizing the derived RXRECCLK.

For further clarity, the TXUSRCLK is used to clock data from the FPGA fabric to the TX FIFO. The FIFO depth accounts for the slight phase difference between these two clocks. If the clocks are locked in frequency, then the FIFO acts much like a pass-through buffer.

The receiver can be configured to reverse the RXP and RXN inputs. This can be useful in the event that printed circuit board traces have been reversed.

Receiver Lock Control

The CDR circuits will lock to the reference clock automatically if the data is not present. For proper operation, the frequency of the reference clock must be within ±100 ppm of the nominal frequency.

During normal operation, the receiver PLL automatically locks to incoming data (when present) or to the local reference clock (when data is not present). This is the default configuration for all primitives. This function can be overridden via the PMARXLOCKSEL port

When receive PLL lock is forced to the local reference, phase information from the incoming data stream is ignored. Data continues to be sampled, but synchronous to the local reference rather than relative to edges in the data stream.

Receive Equalization

In addition to transmit emphasis, the RocketIO X MGT provides a programmable active receive equalization feature to further compensate the effects of channel attenuation at high frequencies.

By adjusting RXFER, the right amount of equalization can be added to reverse the signal degradation caused by a printed circuit board, a backplane, or a line/switch card. RXFER can be set through software configuration or the PMA Attribute Bus.

Receiver Termination

On-chip termination is provided at the receiver, eliminating the need for external termination. The receiver termination supply (V_{TRX}) is the center tap of differential termination to

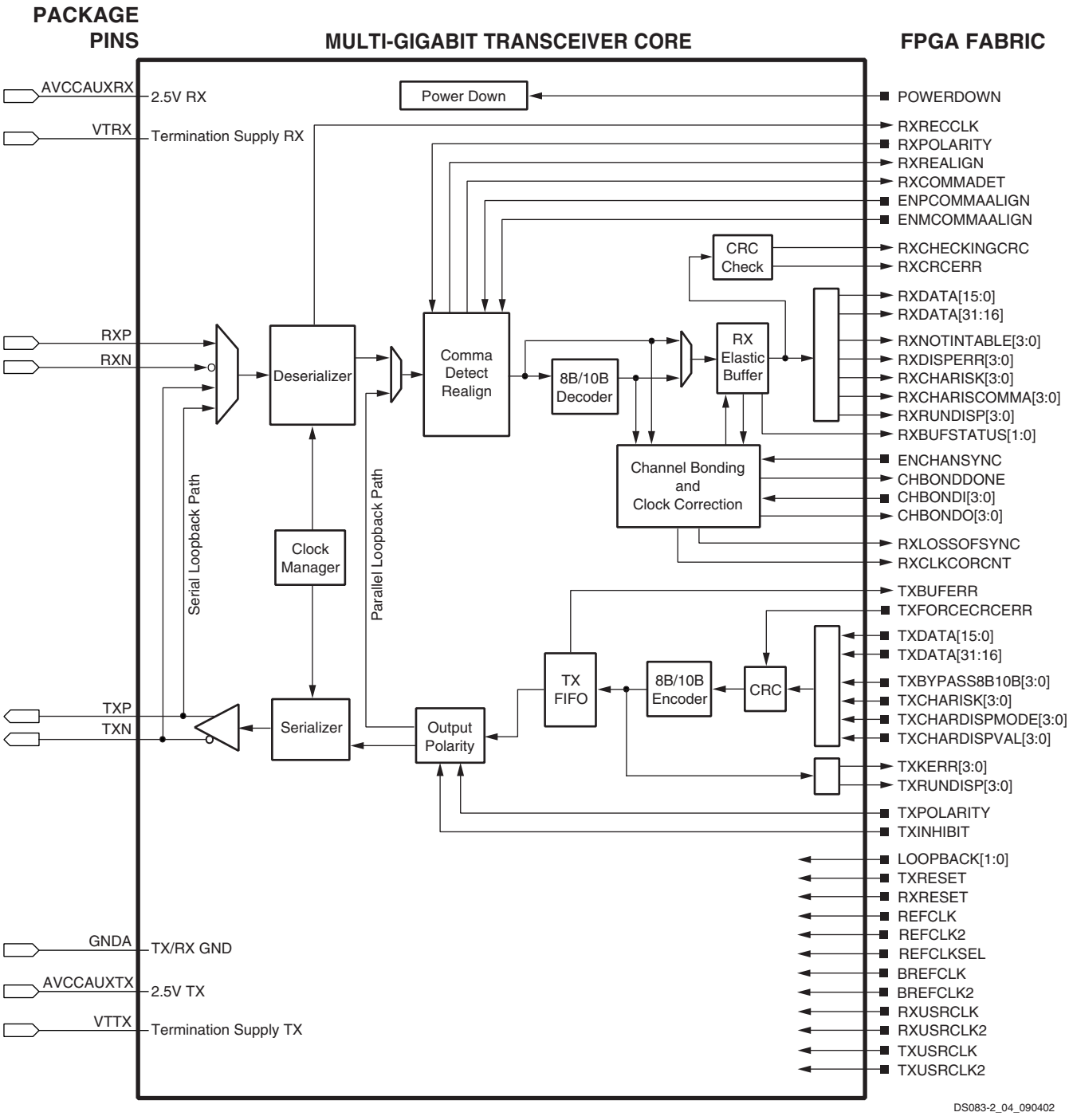


Figure 10: **RocketIO Transceiver Block Diagram**

Output Swing and Pre-emphasis

The output swing and pre-emphasis levels of the RocketIO MGTs are fully programmable. Each is controlled via attributes at configuration, but can be modified via partial reconfiguration.

The programmable output swing control can adjust the differential output level between 400 mV and 800 mV in four increments of 100 mV.

With pre-emphasis, the differential voltage swing is boosted to create a stronger rising waveform. This method compensates for high-frequency loss in the transmission media that would otherwise limit the magnitude of this waveform. Lossy transmission lines cause the dissipation of electrical energy. This pre-emphasis technique extends the distance that signals can be driven down lossy line media and increases the signal-to-noise ratio at the receiver.

Table 5: **Clock Ratios for Various Data Widths**

Fabric Data Width	Frequency Ratio of USRCLK:USRCLK2
1-byte	1:2 (1)
2-byte	1:1
4-byte	2:1 (1)

Notes:
1. Each edge of slower clock must align with falling edge of faster clock.

FPGA Transmit Interface

The FPGA can send either one, two, or four characters of data to the transmitter. Each character can be either 8 bits or 10 bits wide. If 8-bit data is applied, the additional inputs become control signals for the 8B/10B encoder. When the 8B/10B encoder is bypassed, the 10-bit character order is generated as follows:

TXCHARDISPMODE[0] (first bit transmitted)
TXCHARDISPVAL[0]
TXDATA[7:0] (last bit transmitted is TXDATA[0])

Disparity Control

The 8B/10B encoder is initialized with a negative running disparity. Unique control allows forcing the current running disparity state.

TXRUNDISP signals its current running disparity. This may be useful in those cases where there is a need to manipulate the initial running disparity value.

Bits TXCHARDISPMODE and TXCHARDISPVAL control the generation of running disparity before each byte.

For example, the transceiver can generate the sequence

```
K28.5+ K28.5+ K28.5- K28.5-
```

or

```
K28.5- K28.5- K28.5+ K28.5+
```

by specifying inverted running disparity for the second and fourth bytes.

Transmit FIFO

Proper operation of the circuit is only possible if the FPGA clock (TXUSRCLK) is frequency-locked to the reference clock (REFCLK). Phase variations up to one clock cycle are allowable. The FIFO has a depth of four. Overflow or underflow conditions are detected and signaled at the interface. Bypassing of this FIFO is programmable.

8B/10B Encoder

Note: In the RocketIO transceiver, the most-significant byte is sent first; in the RocketIO X transceiver, the least-significant byte is sent first.

A bypassable 8B/10B encoder is included. The encoder uses the same 256 data characters and 12 control characters used by Gigabit Ethernet, Fibre Channel, and InfiniBand.

The encoder accepts 8 bits of data along with a K-character signal for a total of 9 bits per character applied, and generates a 10 bit character for transmission. If the K-character signal is High, the data is encoded into one of the twelve possible K-characters available in the 8B/10B code. If the K-character input is Low, the 8 bits are encoded as standard data. If the K-character input is High, and a user applies other than one of the twelve possible combinations, TXKERR indicates the error.

8B/10B Decoder

Note: In the RocketIO transceiver, the most-significant byte is sent first; in the RocketIO X transceiver, the least-significant byte is sent first.

An optional 8B/10B decoder is included. A programmable option allows the decoder to be bypassed. When the 8B/10B decoder is bypassed, the 10-bit character order is, for example,

RXCHARISK[0] (first bit received)
RXRUNDISP[0]
RXDATA[7:0] (last bit received is RXDATA[0])

The decoder uses the same table that is used for Gigabit Ethernet, Fibre Channel, and InfiniBand. In addition to decoding all data and K-characters, the decoder has several extra features. The decoder separately detects both “disparity errors” and “out-of-band” errors. A disparity error is the reception of 10-bit character that exists within the 8B/10B table but has an incorrect disparity. An out-of-band error is the reception of a 10-bit character that does not exist within the 8B/10B table. It is possible to obtain an out-of-band error without having a disparity error. The proper disparity is always computed for both legal and illegal characters. The current running disparity is available at the RXRUNDISP signal.

The 8B/10B decoder performs a unique operation if out-of-band data is detected. If out-of-band data is detected, the decoder signals the error and passes the illegal 10-bits through and places them on the outputs. This can be used for debugging purposes if desired.

The decoder also signals the reception of one of the 12 valid K-characters. In addition, a programmable comma detect is included. The comma detect signal registers a comma on the receipt of any comma+, comma–, or both. Since the comma is defined as a 7-bit character, this includes several out-of-band characters. Another option allows the decoder to detect only the three defined commas (K28.1, K28.5, and K28.7) as comma+, comma–, or both. In total, there are six possible options, three for valid commas and three for "any comma."

Note that all bytes (1, 2, or 4) at the RX FPGA interface each have their own individual 8B/10B indicators (K-character, disparity error, out-of-band error, current running disparity, and comma detect).

Table 11: **LVCMOS Programmable Currents (Sink and Source)**

SelectIO-Ultra	Programmable Current (Worst-Case Guaranteed Minimum)						
LVTTL	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	24 mA
LVCMOS33	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	24 mA
LVCMOS25	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	24 mA
LVCMOS18	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	n/a
LVCMOS15	2 mA	4 mA	6 mA	8 mA	12 mA	16 mA	n/a

Figure 23 shows the SSTL2, SSTL18, and HSTL configurations. HSTL can sink current up to 48 mA. (HSTL IV)

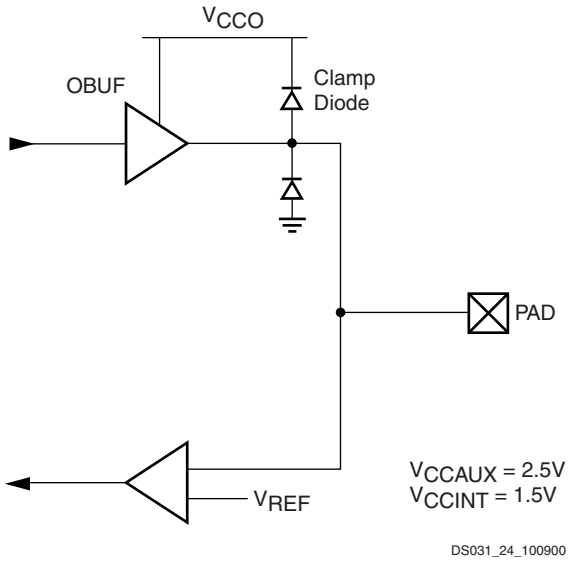


Figure 23: **SSTL or HSTL SelectIO-Ultra Standards**

All pads are protected against damage from electrostatic discharge (ESD) and from over-voltage transients. Virtex-II Pro uses two memory cells to control the configuration of an I/O as an input. This is to reduce the probability of an I/O configured as an input from flipping to an output when subjected to a single event upset (SEU) in space applications.

Prior to configuration, all outputs not involved in configuration are forced into their high-impedance state. The pull-down resistors and the weak-keeper circuits are inactive. The dedicated pin HSWAP_EN controls the pull-up resistors prior to configuration. By default, HSWAP_EN is set High, which disables the pull-up resistors on user I/O pins. When HSWAP_EN is set Low, the pull-up resistors are activated on user I/O pins.

All Virtex-II Pro IOBs (except RocketIO transceiver pins) support IEEE 1149.1 and IEEE 1532 compatible Boundary-Scan testing.

Input Path

The Virtex-II Pro IOB input path routes input signals directly to internal logic and / or through an optional input flip-flop or latch, or through the DDR input registers. An optional delay element at the D-input of the storage element eliminates pad-to-pad hold time. The delay is matched to the internal clock-distribution delay of the Virtex-II Pro device, and when used, assures that the pad-to-pad hold time is zero.

Each input buffer can be configured to conform to any of the low-voltage signaling standards supported. In some of these standards the input buffer utilizes a user-supplied threshold voltage, V_{REF}. The need to supply V_{REF} imposes constraints on which standards can be used in the same bank. See I/O banking description.

Output Path

The output path includes a 3-state output buffer that drives the output signal onto the pad. The output and / or the 3-state signal can be routed to the buffer directly from the internal logic or through an output / 3-state flip-flop or latch, or through the DDR output / 3-state registers.

Each output driver can be individually programmed for a wide range of low-voltage signaling standards. In most signaling standards, the output High voltage depends on an externally supplied V_{CCO} voltage. The need to supply V_{CCO} imposes constraints on which standards can be used in the same bank. See I/O banking description.

I/O Banking

Some of the I/O standards described above require V_{CCO} and V_{REF} voltages. These voltages are externally supplied and connected to device pins that serve groups of IOB blocks, called banks. Consequently, restrictions exist about which I/O standards can be combined within a given bank.

Eight I/O banks result from dividing each edge of the FPGA into two banks, as shown in Figure 24 and Figure 25. Each bank has multiple V_{CCO} pins, all of which must be connected to the same voltage. This voltage is determined by the output standards in use.

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
6	IO_L55P_6	T2			
6	IO_L55N_6	T1			
6	IO_L57P_6	R9			
6	IO_L57N_6/VREF_6	R8			
6	IO_L59P_6	R6			
6	IO_L59N_6	P6			
6	IO_L60P_6	R5			
6	IO_L60N_6	R4			
6	IO_L85P_6	R2			
6	IO_L85N_6	R1			
6	IO_L87P_6	P9			
6	IO_L87N_6/VREF_6	P8			
6	IO_L89P_6	P5			
6	IO_L89N_6	P4			
6	IO_L90P_6	P3			
6	IO_L90N_6	P2			
7	IO_L90P_7	N2			
7	IO_L90N_7	N3			
7	IO_L88P_7	N4			
7	IO_L88N_7/VREF_7	N5			
7	IO_L86P_7	N8			
7	IO_L86N_7	N9			
7	IO_L85P_7	M1			
7	IO_L85N_7	M2			
7	IO_L60P_7	M4			
7	IO_L60N_7	M5			
7	IO_L58P_7	N6			
7	IO_L58N_7/VREF_7	M6			
7	IO_L56P_7	M8			
7	IO_L56N_7	M9			
7	IO_L55P_7	L1			
7	IO_L55N_7	L2			
7	IO_L54P_7	L5			
7	IO_L54N_7	L6			

Table 7: **FG676/FGG676 — XC2VP20, XC2VP30, and XC2VP40**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP20	XC2VP30	XC2VP40
7	IO_L04N_7/VREF_7	E2			
7	IO_L03P_7	F5			
7	IO_L03N_7	E4			
7	IO_L02P_7	D1			
7	IO_L02N_7	D2			
7	IO_L01P_7/VRN_7	C1			
7	IO_L01N_7/VRP_7	C2			
0	VCCO_0	C5			
0	VCCO_0	C8			
0	VCCO_0	D11			
0	VCCO_0	J10			
0	VCCO_0	J11			
0	VCCO_0	K12			
0	VCCO_0	K13			
1	VCCO_1	C19			
1	VCCO_1	C22			
1	VCCO_1	D16			
1	VCCO_1	J16			
1	VCCO_1	J17			
1	VCCO_1	K14			
1	VCCO_1	K15			
2	VCCO_2	E24			
2	VCCO_2	H24			
2	VCCO_2	K18			
2	VCCO_2	L18			
2	VCCO_2	L23			
2	VCCO_2	M17			
2	VCCO_2	N17			
3	VCCO_3	P17			
3	VCCO_3	R17			
3	VCCO_3	T18			
3	VCCO_3	T23			
3	VCCO_3	U18			
3	VCCO_3	W24			

Table 8: **FF672 — XC2VP2, XC2VP4, and XC2VP7**

Bank	Pin Description	Pin Number	No Connects		
			XC2VP2	XC2VP4	XC2VP7
7	IO_L44P_7	G24	NC		
7	IO_L44N_7	G23	NC		
7	IO_L43P_7	G22	NC		
7	IO_L43N_7	G21	NC		
7	IO_L42P_7	F25	NC	NC	NC
7	IO_L42N_7	F24	NC	NC	NC
7	IO_L40P_7	F23	NC	NC	NC
7	IO_L40N_7/VREF_7	F22	NC	NC	NC
7	IO_L06P_7	E26			
7	IO_L06N_7	E25			
7	IO_L05P_7	E24			
7	IO_L05N_7	E23			
7	IO_L04P_7	D26			
7	IO_L04N_7/VREF_7	D25			
7	IO_L03P_7	C26			
7	IO_L03N_7	C25			
7	IO_L02P_7	B26			
7	IO_L02N_7	A25			
7	IO_L01P_7/VRN_7	D24			
7	IO_L01N_7/VRP_7	C23			
0	VCCO_0	C17			
0	VCCO_0	C20			
0	VCCO_0	H17			
0	VCCO_0	H18			
0	VCCO_0	J14			
0	VCCO_0	J15			
0	VCCO_0	J16			
1	VCCO_1	C7			
1	VCCO_1	H9			
1	VCCO_1	C10			
1	VCCO_1	H10			
1	VCCO_1	J11			
1	VCCO_1	J12			
1	VCCO_1	J13			
2	VCCO_2	G2			
2	VCCO_2	J8			

Table 9: **FF896 — XC2VP7, XC2VP20, XC2VPX20, and XC2VP30**

Bank	Pin Description		Pin Number	No Connects		
	Virtex-II Pro devices	XC2VPX20 (if Different)		XC2VP7	XC2VP20, XC2VPX20	XC2VP30
0	IO_L01N_0/VRP_0		E25			
0	IO_L01P_0/VRN_0		E24			
0	IO_L02N_0		F24			
0	IO_L02P_0		F23			
0	IO_L03N_0		E23			
0	IO_L03P_0/VREF_0		E22			
0	IO_L05_0/No_Pair		G23			
0	IO_L06N_0		H22			
0	IO_L06P_0		G22			
0	IO_L07N_0		F22			
0	IO_L07P_0		F21			
0	IO_L08N_0		D24			
0	IO_L08P_0		C24			
0	IO_L09N_0		H21			
0	IO_L09P_0/VREF_0		G21			
0	IO_L37N_0		E21			
0	IO_L37P_0		D21			
0	IO_L38N_0		D23			
0	IO_L38P_0		C23			
0	IO_L39N_0		H20			
0	IO_L39P_0		G20			
0	IO_L43N_0		E20			
0	IO_L43P_0		D20			
0	IO_L44N_0		B23			
0	IO_L44P_0		A23			
0	IO_L45N_0		H19			
0	IO_L45P_0/VREF_0		G19			
0	IO_L46N_0		E19	NC		
0	IO_L46P_0		E18	NC		
0	IO_L47N_0		C22	NC		
0	IO_L47P_0		B22	NC		
0	IO_L48N_0		F20	NC		
0	IO_L48P_0		F19	NC		
0	IO_L49N_0		G17	NC		
0	IO_L49P_0		F17	NC		
0	IO_L50_0/No_Pair		B21	NC		

Table 10: **FF1152 — XC2VP20, XC2VP30, XC2VP40, and XC2VP50**

Bank	Pin Description	Pin Number	No Connects			
			XC2VP20	XC2VP30	XC2VP40	XC2VP50
6	IO_L53P_6	W25				
6	IO_L53N_6	W26				
6	IO_L54P_6	AB33				
6	IO_L54N_6	AA33				
6	IO_L55P_6	Y28				
6	IO_L55N_6	Y29				
6	IO_L56P_6	W27				
6	IO_L56N_6	W28				
6	IO_L57P_6	Y31				
6	IO_L57N_6/VREF_6	Y32				
6	IO_L58P_6	W29				
6	IO_L58N_6	W30				
6	IO_L59P_6	W24				
6	IO_L59N_6	V24				
6	IO_L60P_6	AA34				
6	IO_L60N_6	Y34				
6	IO_L85P_6	W31				
6	IO_L85N_6	W32				
6	IO_L86P_6	V25				
6	IO_L86N_6	V26				
6	IO_L87P_6	Y33				
6	IO_L87N_6/VREF_6	W33				
6	IO_L88P_6	V29				
6	IO_L88N_6	V30				
6	IO_L89P_6	V27				
6	IO_L89N_6	V28				
6	IO_L90P_6	V31				
6	IO_L90N_6	V32				
7	IO_L90P_7	U32				
7	IO_L90N_7	U31				
7	IO_L89P_7	U28				
7	IO_L89N_7	U27				
7	IO_L88P_7	V33				
7	IO_L88N_7/VREF_7	U33				
7	IO_L87P_7	U30				
7	IO_L87N_7	U29				
7	IO_L86P_7	U26				

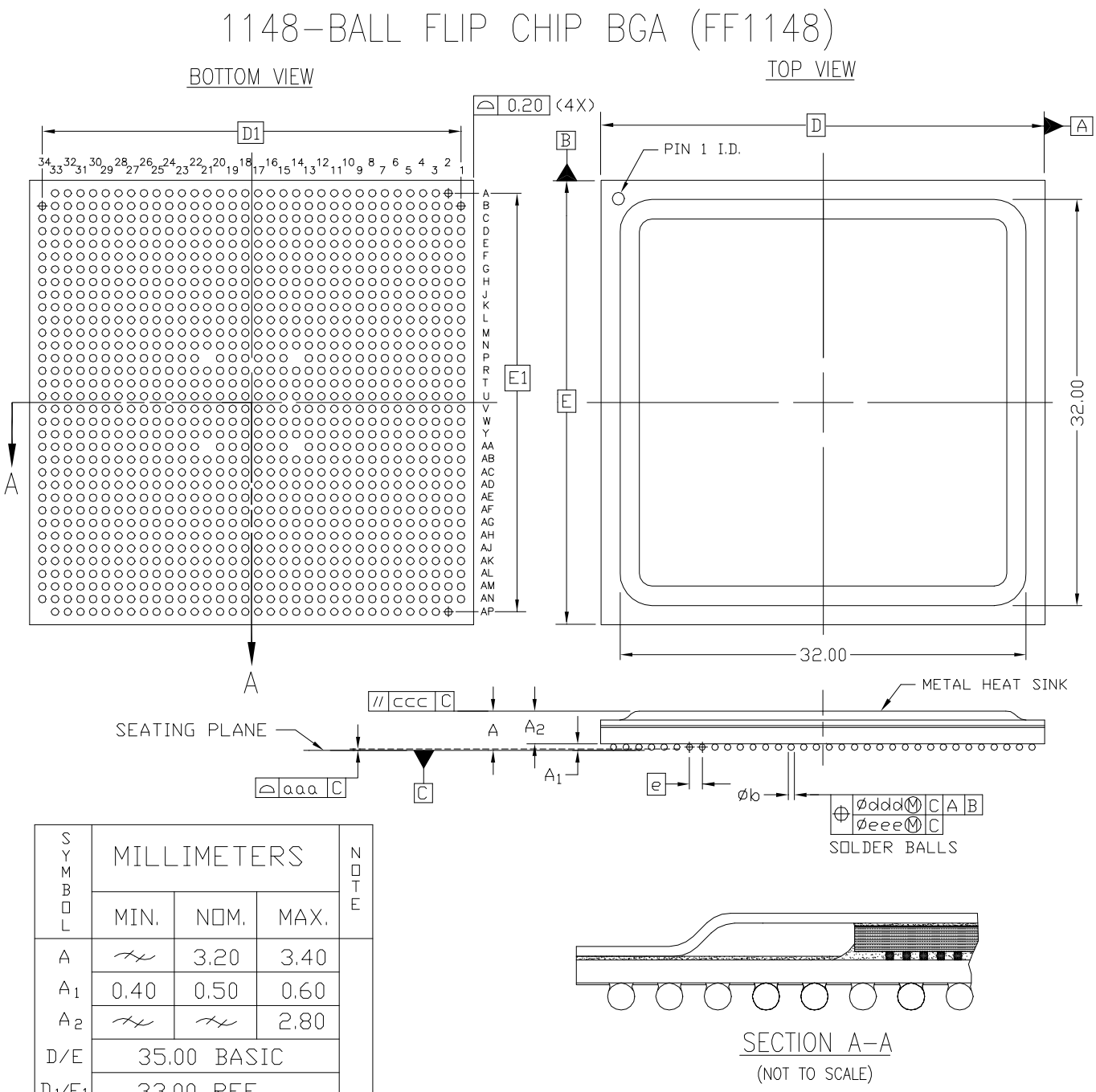
Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
3	IO_L36N_3	AE4		
3	IO_L36P_3	AF4		
3	IO_L35N_3	AC10		
3	IO_L35P_3	AD10		
3	IO_L34N_3	AE1		
3	IO_L34P_3	AE2		
3	IO_L33N_3/VREF_3	AF6		
3	IO_L33P_3	AF7		
3	IO_L32N_3	AC8		
3	IO_L32P_3	AC9		
3	IO_L31N_3	AF2		
3	IO_L31P_3	AF3		
3	IO_L30N_3	AG5		
3	IO_L30P_3	AG6		
3	IO_L29N_3	AD9		
3	IO_L29P_3	AE9		
3	IO_L28N_3	AG4		
3	IO_L28P_3	AH3		
3	IO_L27N_3/VREF_3	AG2		
3	IO_L27P_3	AG3		
3	IO_L26N_3	AD7		
3	IO_L26P_3	AE7		
3	IO_L25N_3	AH6		
3	IO_L25P_3	AH7		
3	IO_L24N_3	AH5		
3	IO_L24P_3	AJ5		
3	IO_L23N_3	AE8		
3	IO_L23P_3	AF8		
3	IO_L22N_3	AH1		
3	IO_L22P_3	AH2		
3	IO_L21N_3/VREF_3	AJ6		
3	IO_L21P_3	AK6		
3	IO_L20N_3	AG7		
3	IO_L20P_3	AG8		
3	IO_L19N_3	AJ3		
3	IO_L19P_3	AJ4		
3	IO_L18N_3	AJ1		
3	IO_L18P_3	AJ2		

Table 11: **FF1148 — XC2VP40 and XC2VP50**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP40	XC2VP50
N/A	VCCINT	M12		
N/A	VCCINT	AD11		
N/A	VCCINT	L11		
N/A	VCCAUX	AN34		
N/A	VCCAUX	AG34		
N/A	VCCAUX	U34		
N/A	VCCAUX	H34		
N/A	VCCAUX	B34		
N/A	VCCAUX	AP33		
N/A	VCCAUX	A33		
N/A	VCCAUX	AP27		
N/A	VCCAUX	A27		
N/A	VCCAUX	AP17		
N/A	VCCAUX	A17		
N/A	VCCAUX	AP8		
N/A	VCCAUX	A8		
N/A	VCCAUX	AP2		
N/A	VCCAUX	A2		
N/A	VCCAUX	AN1		
N/A	VCCAUX	AG1		
N/A	VCCAUX	U1		
N/A	VCCAUX	H1		
N/A	VCCAUX	B1		
N/A	GND	AK34		
N/A	GND	AF34		
N/A	GND	AB34		
N/A	GND	W34		
N/A	GND	V34		
N/A	GND	T34		
N/A	GND	N34		
N/A	GND	J34		
N/A	GND	E34		
N/A	GND	AN33		
N/A	GND	B33		
N/A	GND	AM32		
N/A	GND	C32		
N/A	GND	AP30		
N/A	GND	AK30		

FF1148 Flip-Chip Fine-Pitch BGA Package Specifications (1.00mm pitch)



SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	---	3.20	3.40	
A_1	0.40	0.50	0.60	
A_2	---	---	2.80	
D/E	35.00 BASIC			
D_1/E_1	33.00 REF			
e	1.00 BASIC			
øb	0.50	0.60	0.70	
aaa	---	---	0.20	
ccc	---	---	0.35	
ddd	---	---	0.30	
eee	---	---	0.10	
M	34			2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAR-1 (DEPOPULATED)

Figure 7: **FF1148 Flip-Chip Fine-Pitch BGA Package Specifications**

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
1	IO_L64N_1	E18		
1	IO_L64P_1	D18		
1	IO_L60N_1	G18		
1	IO_L60P_1	F18		
1	IO_L59N_1	L18		
1	IO_L59P_1	K18		
1	IO_L58N_1	J18		
1	IO_L58P_1	H18		
1	IO_L57N_1/VREF_1	D17		
1	IO_L57P_1	C17		
1	IO_L56N_1	N18		
1	IO_L56P_1	M18		
1	IO_L55N_1	E17		
1	IO_L55P_1	E16		
1	IO_L54N_1	G17		
1	IO_L54P_1	F16		
1	IO_L53_1/No_Pair	J17		
1	IO_L50_1/No_Pair	H17		
1	IO_L49N_1	J16		
1	IO_L49P_1	H16		
1	IO_L48N_1	D15		
1	IO_L48P_1	C15		
1	IO_L47N_1	L17		
1	IO_L47P_1	K16		
1	IO_L46N_1	F15		
1	IO_L46P_1	E15		
1	IO_L45N_1/VREF_1	H15		
1	IO_L45P_1	G15		
1	IO_L44N_1	N17		
1	IO_L44P_1	M17		
1	IO_L43N_1	D14		
1	IO_L43P_1	C14		
1	IO_L39N_1	F14		
1	IO_L39P_1	E14		
1	IO_L38N_1	M16		
1	IO_L38P_1	M15		
1	IO_L37N_1	H14		
1	IO_L37P_1	G14		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
6	IO_L53P_6	AB30		
6	IO_L53N_6	AB31		
6	IO_L54P_6	AC38		
6	IO_L54N_6	AC39		
6	IO_L55P_6	AC34		
6	IO_L55N_6	AC35		
6	IO_L56P_6	AA28		
6	IO_L56N_6	AA29		
6	IO_L57P_6	AB38		
6	IO_L57N_6/VREF_6	AB39		
6	IO_L58P_6	AB36		
6	IO_L58N_6	AB37		
6	IO_L59P_6	AA30		
6	IO_L59N_6	AA31		
6	IO_L60P_6	AB34		
6	IO_L60N_6	AB35		
6	IO_L85P_6	AB32		
6	IO_L85N_6	AB33		
6	IO_L86P_6	AA27		
6	IO_L86N_6	Y27		
6	IO_L87P_6	AA36		
6	IO_L87N_6/VREF_6	AA37		
6	IO_L88P_6	AA34		
6	IO_L88N_6	AA35		
6	IO_L89P_6	Y28		
6	IO_L89N_6	Y29		
6	IO_L90P_6	AA32		
6	IO_L90N_6	AA33		
7	IO_L90P_7	Y36		
7	IO_L90N_7	Y37		
7	IO_L89P_7	Y31		
7	IO_L89N_7	W31		
7	IO_L88P_7	Y32		
7	IO_L88N_7/VREF_7	Y33		
7	IO_L87P_7	W36		
7	IO_L87N_7	W37		
7	IO_L86P_7	W27		

Table 12: **FF1517 — XC2VP50 and XC2VP70**

Bank	Pin Description	Pin Number	No Connects	
			XC2VP50	XC2VP70
2	VCCO_2	F8		
2	VCCO_2	U7		
2	VCCO_2	Y5		
2	VCCO_2	N4		
2	VCCO_2	J4		
2	VCCO_2	E4		
2	VCCO_2	U3		
2	VCCO_2	E1		
1	VCCO_1	N14		
1	VCCO_1	K13		
1	VCCO_1	F13		
1	VCCO_1	P19		
1	VCCO_1	P18		
1	VCCO_1	P17		
1	VCCO_1	K17		
1	VCCO_1	F17		
1	VCCO_1	P16		
1	VCCO_1	N16		
1	VCCO_1	P15		
1	VCCO_1	N15		
0	VCCO_0	K27		
0	VCCO_0	F27		
0	VCCO_0	N26		
0	VCCO_0	P25		
0	VCCO_0	N25		
0	VCCO_0	P24		
0	VCCO_0	N24		
0	VCCO_0	P23		
0	VCCO_0	K23		
0	VCCO_0	F23		
0	VCCO_0	P22		
0	VCCO_0	P21		
N/A	CCLK	AJ10		
N/A	PROG_B	D32		
N/A	DONE	AJ11		
N/A	M0	AP31		
N/A	M1	AJ30		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
3	IO_L35N_3		AH11		
3	IO_L35P_3		AH12		
3	IO_L34N_3		AH5		
3	IO_L34P_3		AH6		
3	IO_L33N_3/VREF_3		AH9		
3	IO_L33P_3		AH10		
3	IO_L32N_3		AJ11		
3	IO_L32P_3		AJ12		
3	IO_L31N_3		AJ1		
3	IO_L31P_3		AJ2		
3	IO_L30N_3		AJ5		
3	IO_L30P_3		AJ6		
3	IO_L29N_3		AJ9		
3	IO_L29P_3		AJ10		
3	IO_L28N_3		AJ7		
3	IO_L28P_3		AJ8		
3	IO_L27N_3/VREF_3		AK1		
3	IO_L27P_3		AK2		
3	IO_L26N_3		AK11		
3	IO_L26P_3		AK12		
3	IO_L25N_3		AK3		
3	IO_L25P_3		AK4		
3	IO_L24N_3		AK5		
3	IO_L24P_3		AK6		
3	IO_L23N_3		AK9		
3	IO_L23P_3		AK10		
3	IO_L22N_3		AK7		
3	IO_L22P_3		AK8		
3	IO_L21N_3/VREF_3		AL2		
3	IO_L21P_3		AL3		
3	IO_L20N_3		AL11		
3	IO_L20P_3		AL12		
3	IO_L19N_3		AL4		
3	IO_L19P_3		AL5		
3	IO_L18N_3		AL7		
3	IO_L18P_3		AL8		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	VCCINT		AF16		
N/A	VCCINT		AG27		
N/A	VCCINT		AG26		
N/A	VCCINT		AG25		
N/A	VCCINT		AG24		
N/A	VCCINT		AG23		
N/A	VCCINT		AG22		
N/A	VCCINT		AG21		
N/A	VCCINT		AG20		
N/A	VCCINT		AG19		
N/A	VCCINT		AG18		
N/A	VCCINT		AG17		
N/A	VCCINT		AG16		
N/A	VCCINT		AH28		
N/A	VCCINT		AH27		
N/A	VCCINT		AH26		
N/A	VCCINT		AH17		
N/A	VCCINT		AH16		
N/A	VCCINT		AH15		
N/A	VCCINT		AJ29		
N/A	VCCINT		AJ28		
N/A	VCCINT		AJ27		
N/A	VCCINT		AJ16		
N/A	VCCINT		AJ15		
N/A	VCCINT		AJ14		
N/A	VCCINT		AK30		
N/A	VCCINT		AK13		
N/A	VCCINT		AA27		
N/A	VCCINT		AA16		
N/A	VCCINT		Y27		
N/A	VCCINT		Y16		
N/A	VCCINT		W27		
N/A	VCCINT		W16		
N/A	VCCINT		V27		
N/A	VCCINT		V16		
N/A	VCCINT		U27		

Table 13: **FF1704 — XC2VP70, XC2VPX70, and XC2VP100**

Bank	Pin Description		Pin Number	No Connects	
	Virtex-II Pro Devices	XC2VPX70 (if Different)		XC2VP70, XC2VPX70	XC2VP100
N/A	GND		AE19		
N/A	GND		AE18		
N/A	GND		AE17		
N/A	GND		AE9		
N/A	GND		AE6		
N/A	GND		AF25		
N/A	GND		AF24		
N/A	GND		AF23		
N/A	GND		AF22		
N/A	GND		AF21		
N/A	GND		AF20		
N/A	GND		AF19		
N/A	GND		AF18		
N/A	GND		AG42		
N/A	GND		AG1		
N/A	GND		AH39		
N/A	GND		AH36		
N/A	GND		AH7		
N/A	GND		AH4		
N/A	GND		AL42		
N/A	GND		AL1		
N/A	GND		AM22		
N/A	GND		AM21		
N/A	GND		AN39		
N/A	GND		AN4		
N/A	GND		AP34		
N/A	GND		AP9		
N/A	GND		AR42		
N/A	GND		AR35		
N/A	GND		AR22		
N/A	GND		AR21		
N/A	GND		AR8		
N/A	GND		AR1		
N/A	GND		AT36		
N/A	GND		AT7		
N/A	GND		AU37		

Table 14: **FF1696 — XC2VP100**

Bank	Pin Description	Pin Number	No Connects
			XC2VP100
N/A	VCCAUX	A2	
N/A	VCCAUX	BA1	
N/A	VCCAUX	AY1	
N/A	VCCAUX	AL1	
N/A	VCCAUX	AB1	
N/A	VCCAUX	AA1	
N/A	VCCAUX	M1	
N/A	VCCAUX	C1	
N/A	VCCAUX	B1	
N/A	GND	AV42	
N/A	GND	AP42	
N/A	GND	AK42	
N/A	GND	AF42	
N/A	GND	AC42	
N/A	GND	Y42	
N/A	GND	U42	
N/A	GND	N42	
N/A	GND	J42	
N/A	GND	E42	
N/A	GND	BA41	
N/A	GND	AY41	
N/A	GND	C41	
N/A	GND	B41	
N/A	GND	BA40	
N/A	GND	B40	
N/A	GND	BB38	
N/A	GND	AV38	
N/A	GND	AP38	
N/A	GND	AK38	
N/A	GND	AF38	
N/A	GND	AC38	
N/A	GND	Y38	
N/A	GND	U38	
N/A	GND	N38	
N/A	GND	J38	
N/A	GND	E38	
N/A	GND	A38	